Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.017”**



**.017”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .0035” X .0043”**

**Backside Potential: Collector**

**APPROVED BY:DK DIE SIZE .017” X .017” DATE: 1/26/22**

**MFG: CENTRAL SEMI THICKNESS: .007 P/N:2N2645**

**DG 10.1.2**

#### Rev B, 7/19/02